































Board Stack Report

Stack Up			Layer Stack			
Layer	Board Layer Stack	Flex	Name	Material	Thickness	Constant
1			Top Paste			
2			Top Overlay			
3			Top Solder	Solder Resist	0.010mm	3.5
4			FlexDC Top Coverlay	FC-001	0.012mm	4
5			Top Layer	Copper	0.035mm	
6			Dielectric 1	PP-018	0.152mm	4.3
7			Layer 2	Copper	0.035mm	
8			Dielectric 2	Core-023	0.190mm	4.2
9			Dielectric 10	PP-018	0.152mm	4.3
10			Layer 3	Copper	0.035mm	
11			Dielectric 3	PP-018	0.152mm	4.3
12			Layer 4	Copper	0.035mm	
13			Dielectric 8	PP-018	0.152mm	4.3
14			Dielectric 4	Core-023	0.190mm	4.2
15			Dielectric 9	PP-018	0.152mm	4.3
16			Layer 5	Copper	0.035mm	
17			Dielectric 5	PP-018	0.152mm	4.3
18			Layer 6	Copper	0.035mm	
19			Dielectric 11	PP-018	0.152mm	4.3
20			Dielectric 6	Core-023	0.190mm	4.2
21			Layer 7	Copper	0.035mm	
22			Dielectric 7	PP-018	0.152mm	4.3
23			Bottom Layer	Copper	0.035mm	
24			FlexDC Bottom Coverlay	FC-001	0.012mm	4
25			Bottom Solder	Solder Resist	0.010mm	3.5
26			Bottom Overlay			
27			Bottom Paste			
	Height : 1.481mm	Height : 1.148mm				